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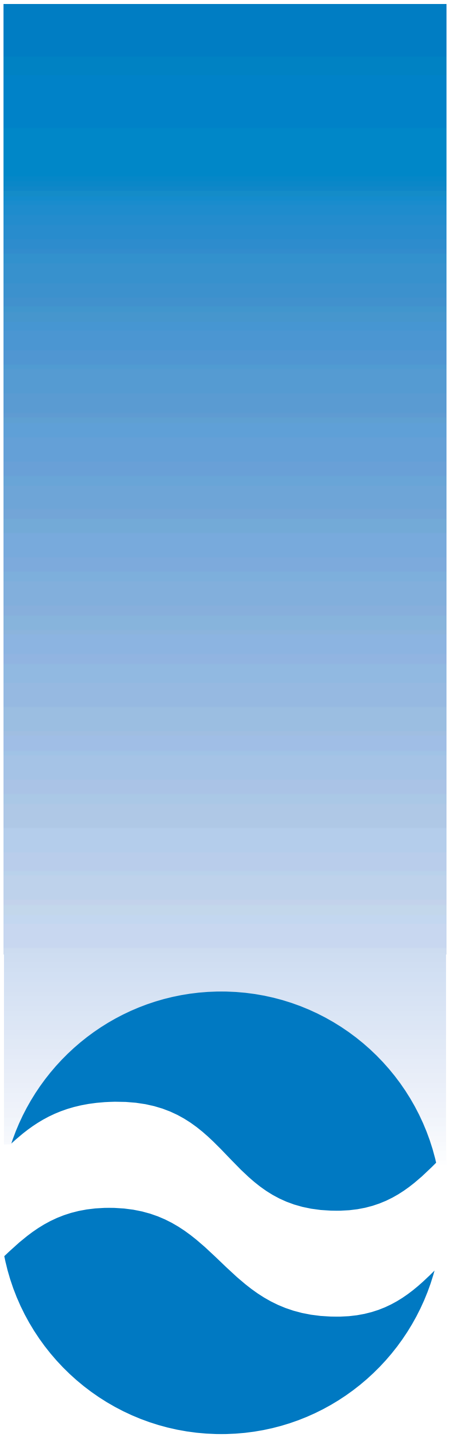

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Requirements for Soldered Electrical and Electronic Assemblies

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- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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Requirements for Soldered Electrical and Electronic Assemblies

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